



Thermal Considerations for Critical CubeSat Missions

Improving system reliability through thermal
management and parts selection

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12th Annual CubeSat Developers' Workshop



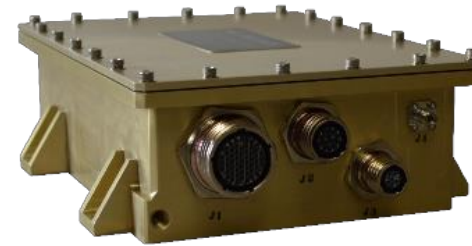
Image Processing Computers



S-Band Transponders



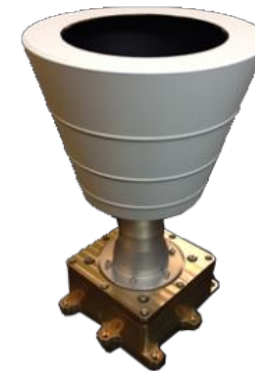
ProtonX Avionics Suites



Ka-Band Transmitters

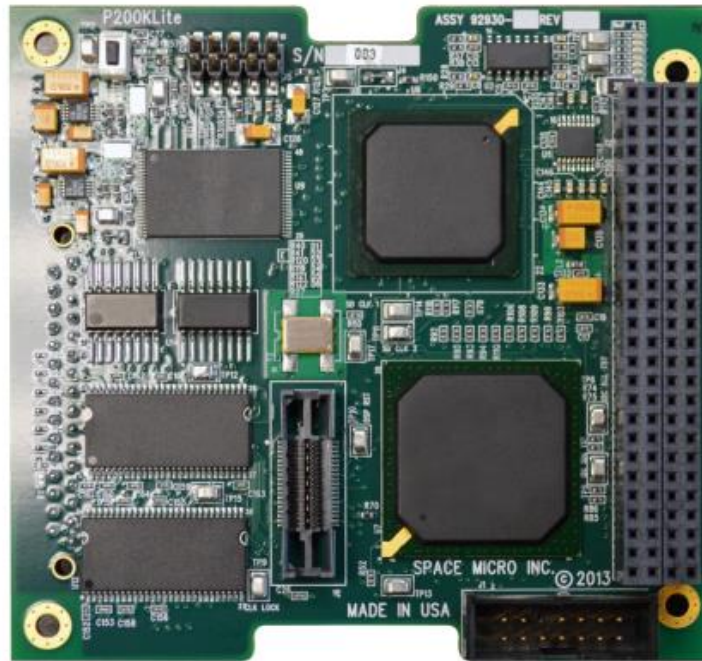


RF Beacons

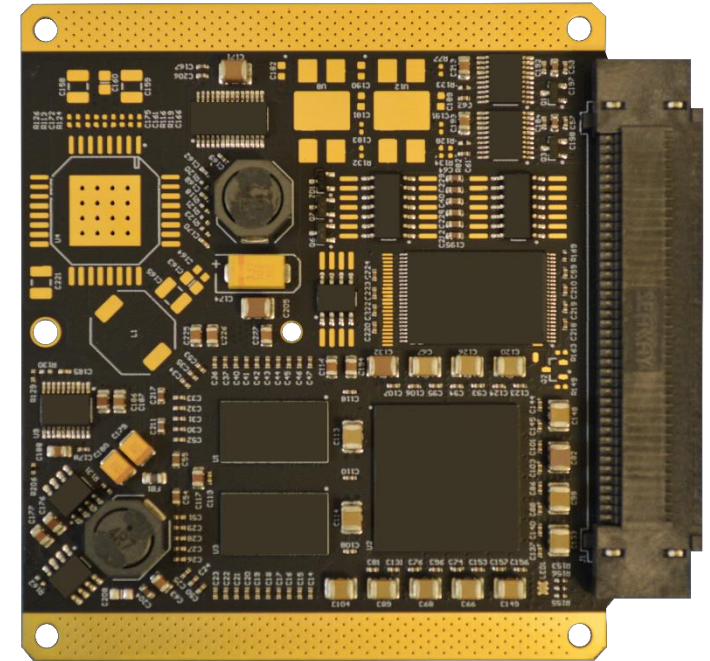


Star Trackers

- High performance single board computers
(Enables reliable on-board processing)
- Parts grade customizable
- Radiation tolerant
(TID & SEE)
- Design for excellent thermal dissipation
(conduction cooled)



P200k-Lite



CSP

Typical Missions

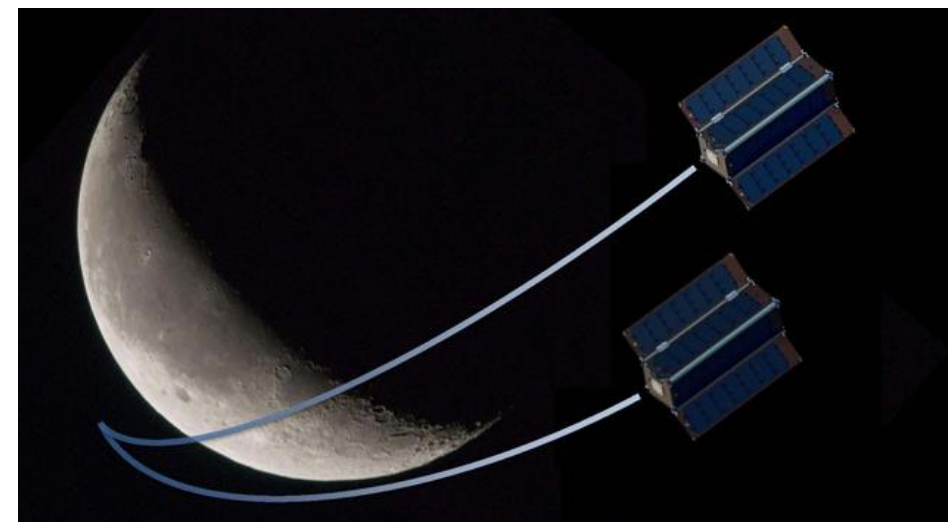


CubeSats deployed from ISS. Image credit: NASA

- Short duration
- Gentle orbits
- High acceptable risk

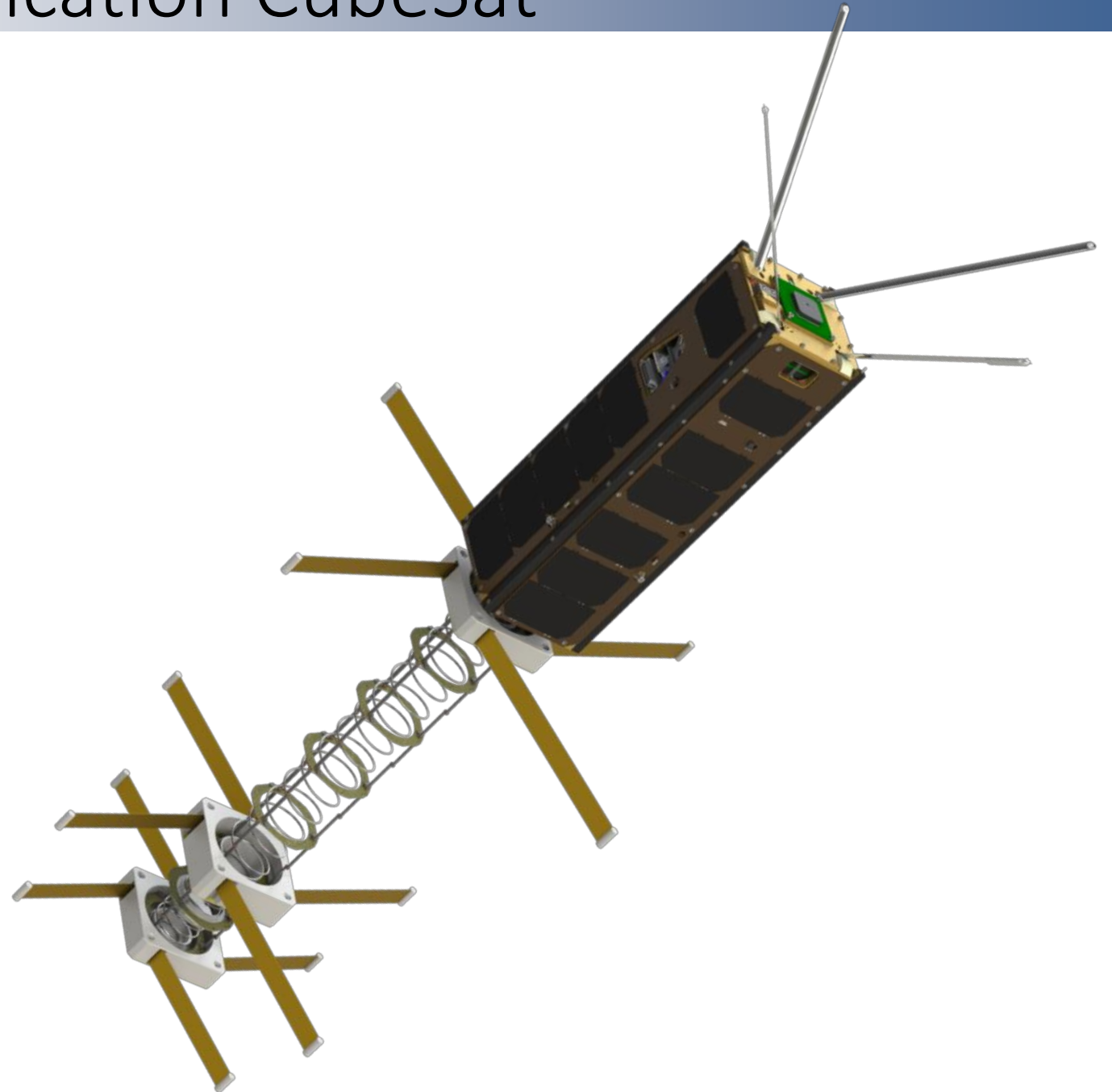
Critical Missions

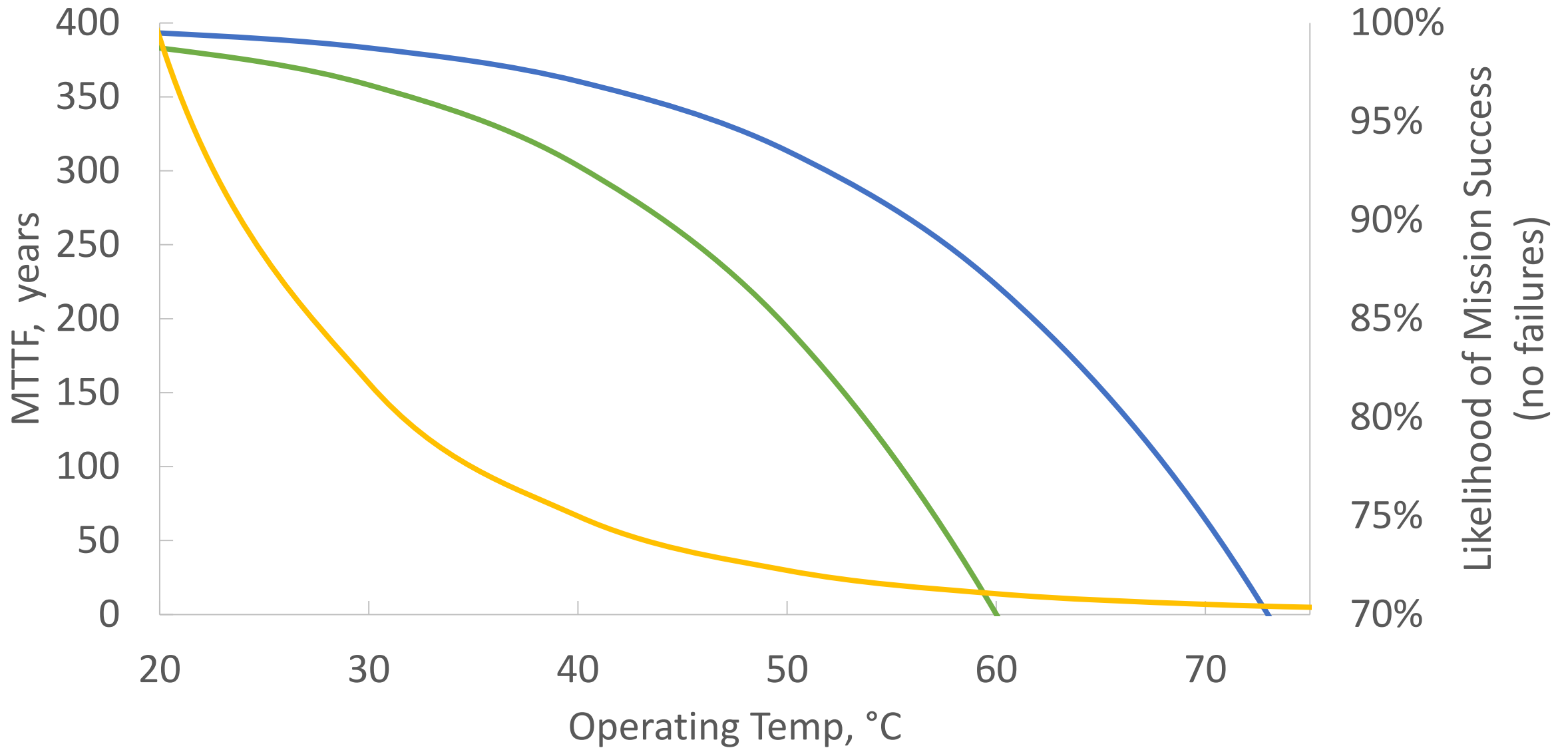
- Increased Capabilities
- Longer duration
- Harsher orbits
- Low acceptable risk



JPL's INSPIRE Project. Image credit: NASA/JPL-Caltech

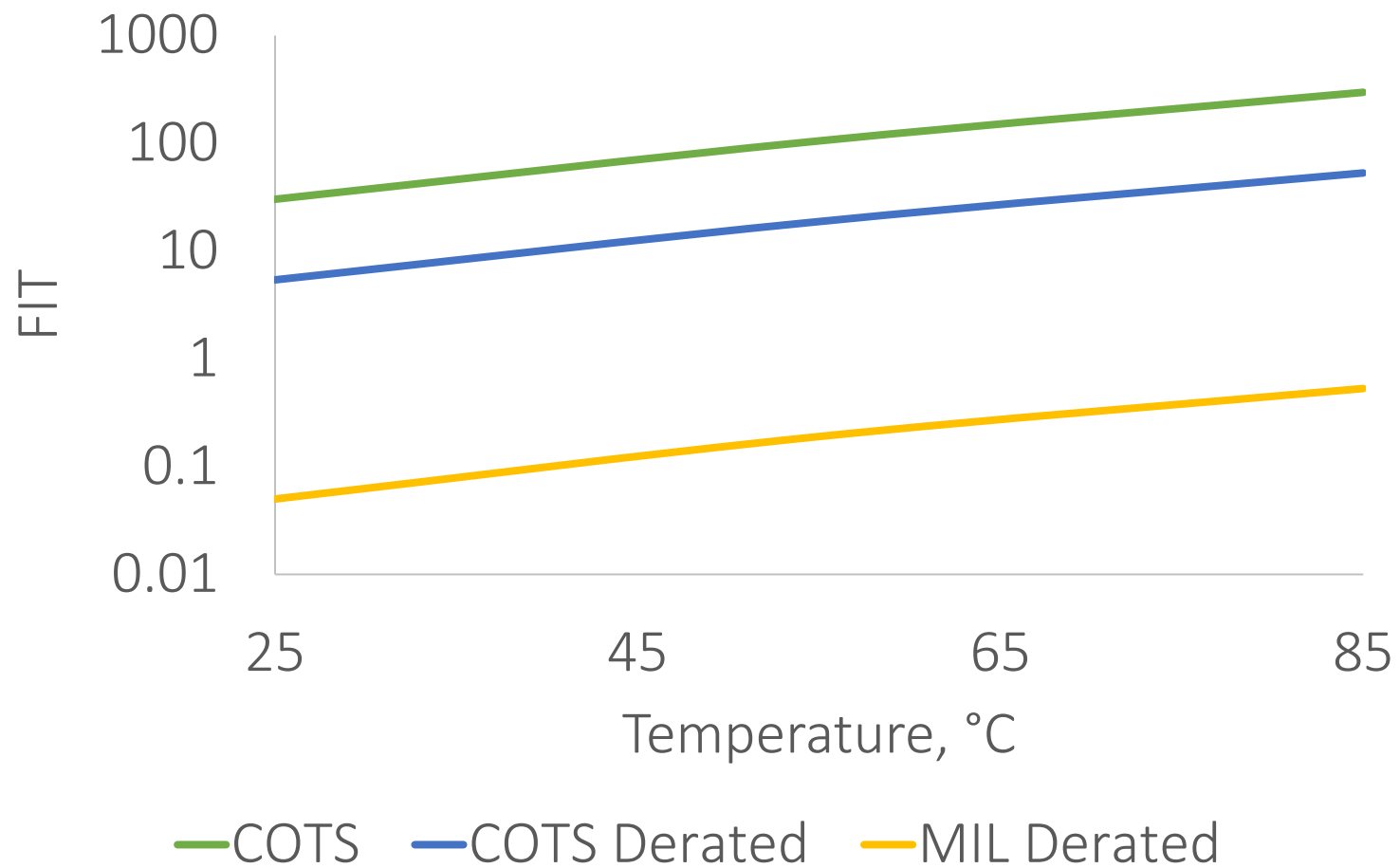
- 3U CubeSat
- Integrated by Space Micro
- Cross-link to GEO
- Dissipate $\approx 30\text{W}$ for significant portion of orbit





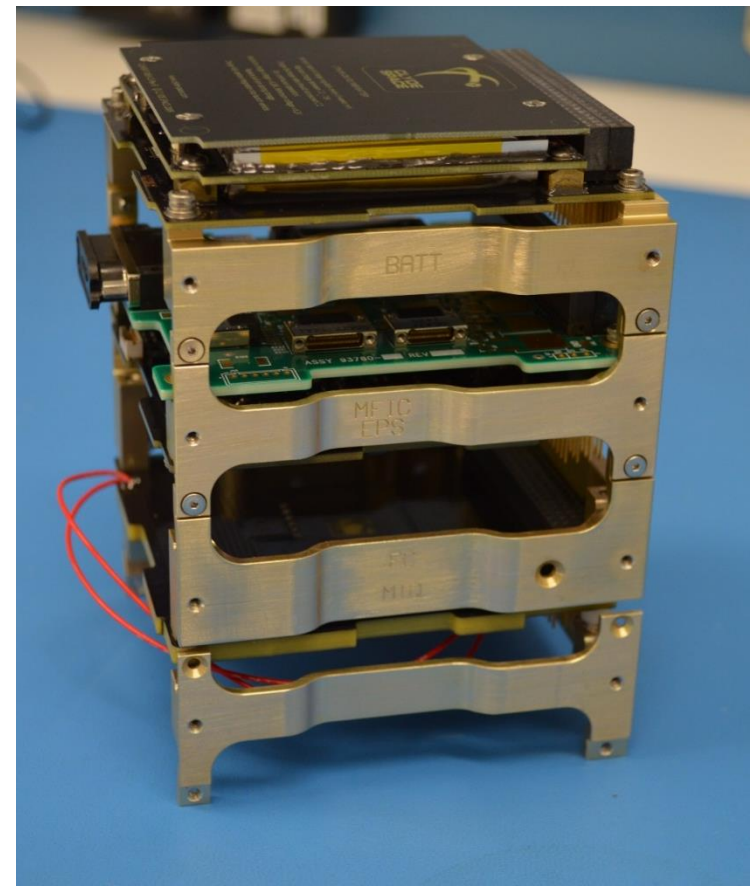
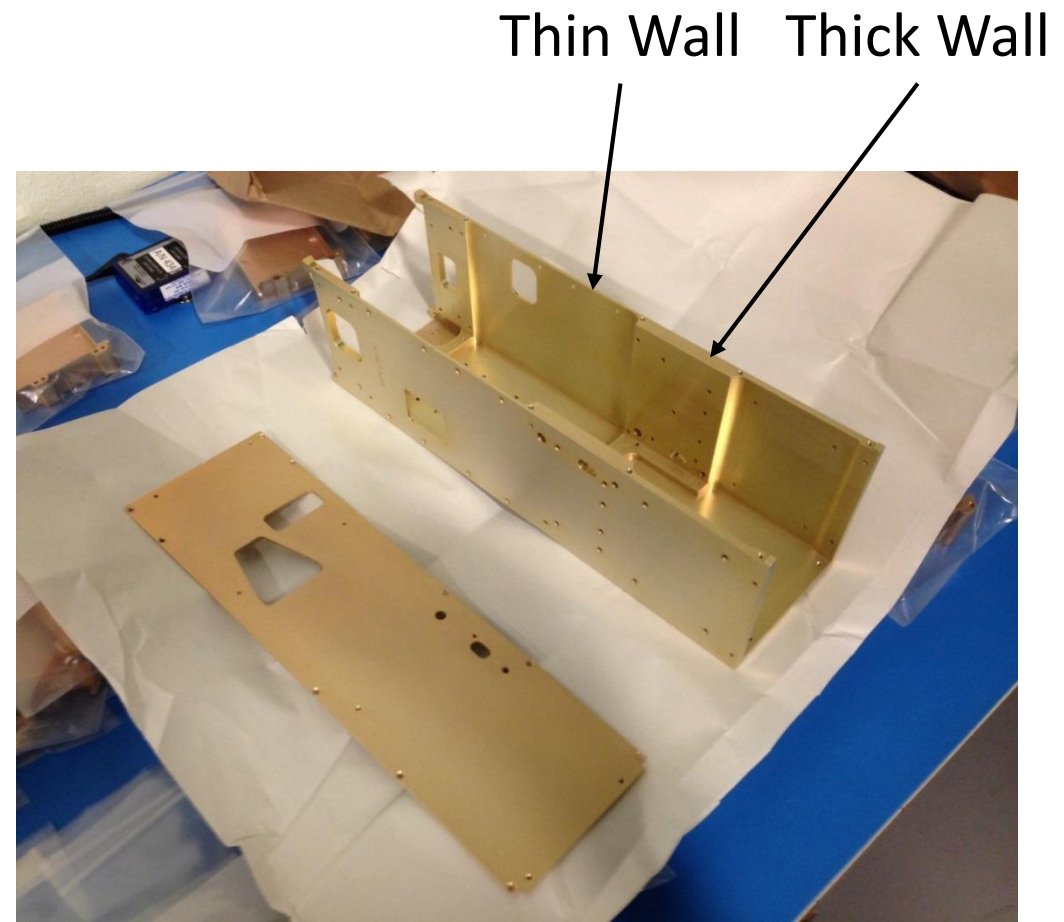
— Reliability at 2 years — Reliability at 5 years — Subsystem MTTF

- Over-design the system (derate the parts)
- Consider temperatures during mechanical design
- Analysis/simulation
- Validate through testing

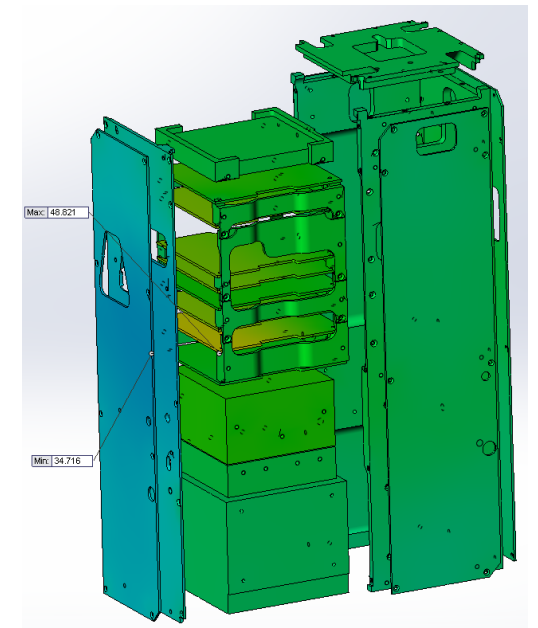
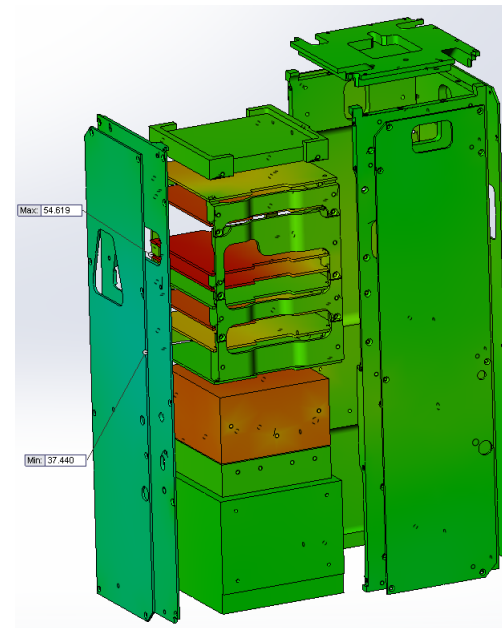
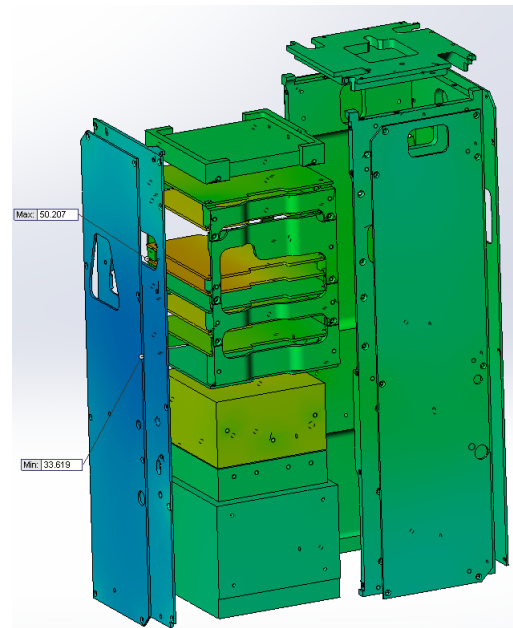
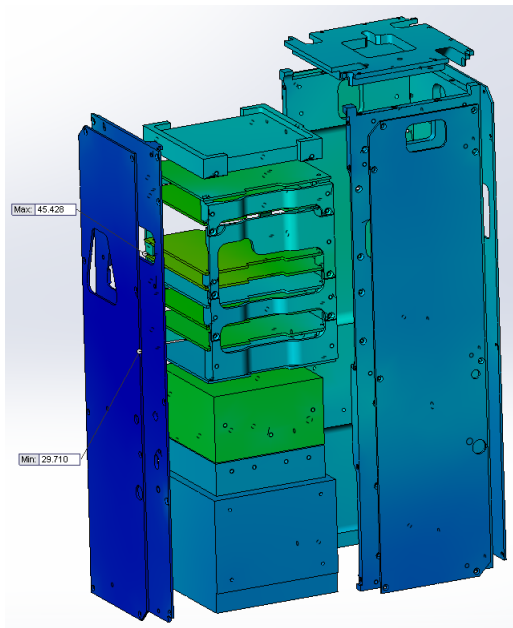
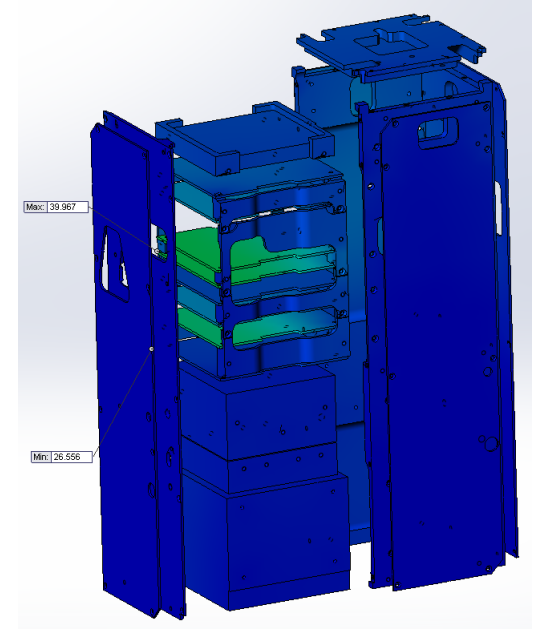
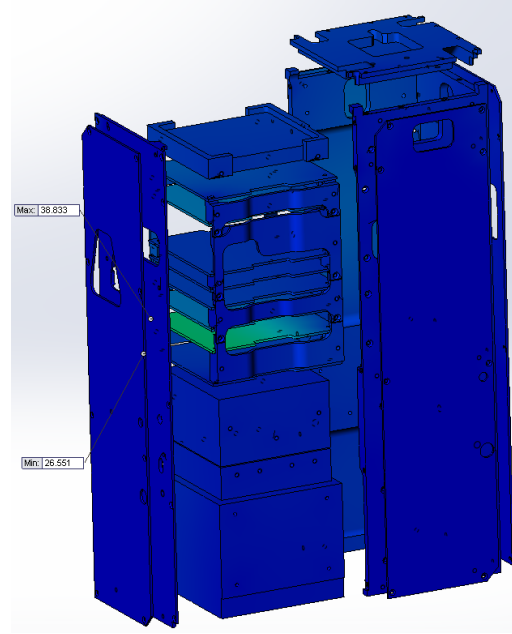
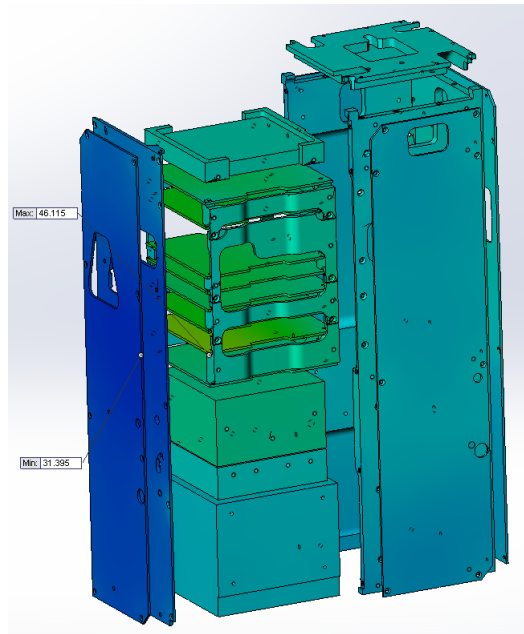


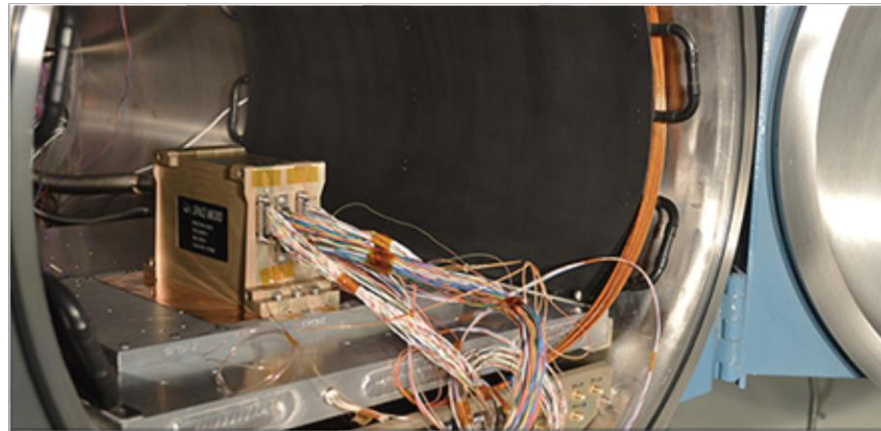
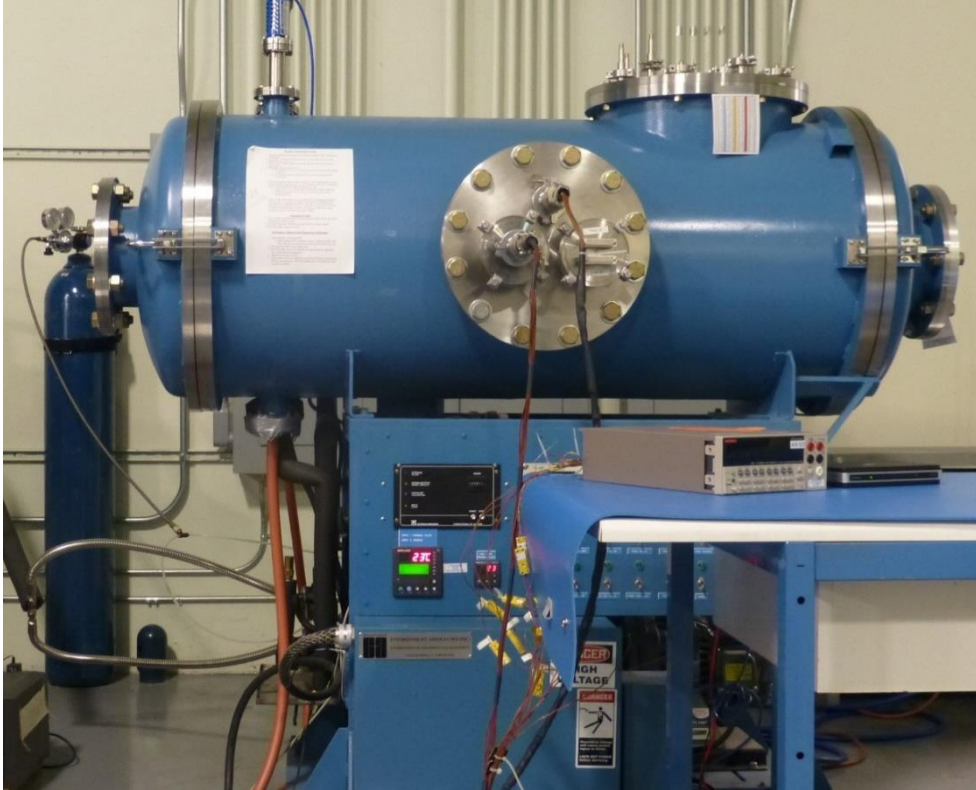
1000pF 0603 Ceramic Capacitor	5V rated COTS @ 5V	50V rated COTS @ 5V	50V rated MIL @ 5V
FIT at 25C	30.2	5.4	0.05
FIT at 55C	105.1	18.8	0.19
FIT at 85C	296.9	53.0	0.53
(Example using MIL-HDBK-217 RevF)			

- Solid outer frame, not skeletonized
- Thicker walls around payload
- Brackets instead of standoffs.



- Implement during design phase
- Compare with test results





- Thermal Vacuum (TVAC)
- Validates model against actual hardware
- Verify operation/survivability at temp
- Adds margin
- Dynamics of the operation

- Why is thermal management important?
 - Improve overall reliability (mission success)
- How are thermal issues addressed and mitigated?
 - Parts selection
 - Mechanical design
 - Analysis/simulation
 - Test